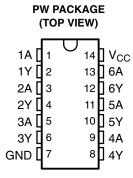
- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 6.5 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation



#### description/ordering information

This hex inverter is designed for 2-V to 5.5-V  $V_{CC}$  operation.

The SN74LV04A contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

The device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### **ORDERING INFORMATION†**

T <sub>A</sub>	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP – PW Tape and reel		SN74LV04ATPWRQ1	LV04AT

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

## FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

### logic diagram, each inverter (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	–0.5 V to $V_{CC}$ + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	113°C/W
Storage temperature range, T <sub>sta</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 5.5 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
.,	I Bala Lavra Danish va Barra	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$		V
$V_{IH}$	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		
		V <sub>CC</sub> = 2 V		0.5	
.,	Land book to a transfer of	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V
$V_{IL}$	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$	
$V_{I}$	Input voltage		0	5.5	V
Vo	Output voltage		0	$V_{CC}$	V
		V <sub>CC</sub> = 2 V		-50	μΑ
	High lavel autout august	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2	
I <sub>OH</sub>	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12	
		V <sub>CC</sub> = 2 V		50	μΑ
	Lave laval autorit augrant	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2	
l <sub>OL</sub>	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20	
$T_A$	Operating free-air temperature		-40	105	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP	MAX	UNIT
	$I_{OH} = -50 \mu\text{A}$	2 V to 5.5 V	V <sub>CC</sub> -0.1			
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	$I_{OH} = -2 \text{ mA}$	2.3 V	2			٧
V <sub>OH</sub>	$I_{OH} = -6 \text{ mA}$	3 V	2.48			V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			
	$I_{OL} = 50 \mu A$	2 V to 5.5 V			0.1	
	I <sub>OL</sub> = 2 mA	2.3 V			0.4	.,
V <sub>OL</sub>	I <sub>OL</sub> = 6 mA	3 V			0.44	V
	I <sub>OL</sub> = 12 mA	4.5 V			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±1	μΑ
I <sub>CC</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
I <sub>off</sub>	$V_1$ or $V_0 = 0$ to 5.5 V	0			5	μΑ
C	V – V or CND	3.3 V		2.3		nE
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		2.3		pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	<sub>4</sub> = 25°C		MAIN	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	Α	Υ	C <sub>L</sub> = 50 pF		10	15.5	1	18	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T <sub>A</sub> = 25°C			MAINI	MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	А	Υ	C <sub>L</sub> = 50 pF		7.3	10.6	1	12	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER FROM (INPUT)		TO LOAD		T <sub>A</sub> = 25°C			MAINI	MAX	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	WAX	UNIT
t <sub>pd</sub>	Α	Υ	C <sub>L</sub> = 50 pF		5.1	7.5	1	8.5	ns

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## noise characteristics, $V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 5)

	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.3	0.8	٧
$V_{OL(V)}$	Quiet output, minimum dynamic V <sub>OL</sub>		-0.1	-0.8	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		3.1		٧
V <sub>IH(D)</sub>	High-level dynamic input voltage	2.31			٧
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

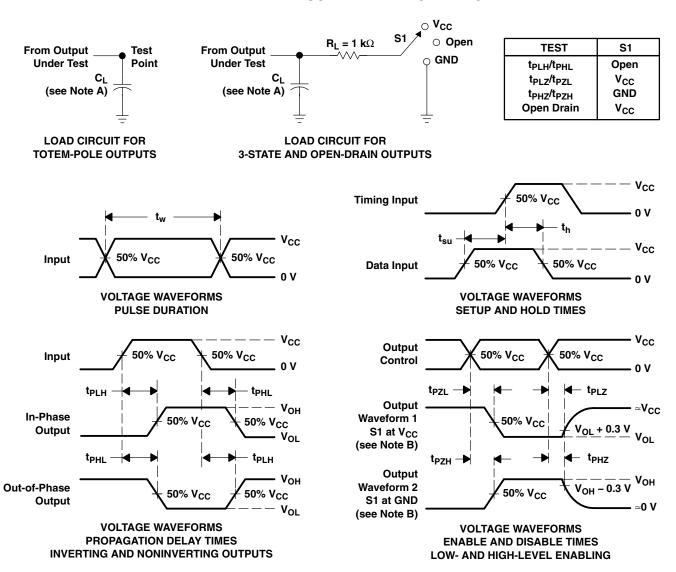
NOTE 5: Characteristics are for surface-mount packages only.

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	V <sub>CC</sub>	TYP	UNIT	
	Dower dissination conscitones	C - 50 nE	f = 10 MHz	3.3 V	9.6	pF
$c_{pd}$	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	11.4	рг



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  3 ns.  $t_f \leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- $\mbox{\rm H.}\;\;\mbox{\rm All}\;\mbox{\rm parameters}\;\mbox{\rm and}\;\mbox{\rm waveforms}\;\mbox{\dot{a}}\mbox{\rm re}\;\mbox{\rm not}\;\mbox{\rm applicable}\;\mbox{\rm to}\;\mbox{\rm all}\;\mbox{\rm devices}.$

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74LV04ATPWRG4Q1	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV04AT
SN74LV04ATPWRG4Q1.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV04AT

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN74LV04A-Q1:

Catalog: SN74LV04A

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### PACKAGE OPTION ADDENDUM

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• Enhanced Product : SN74LV04A-EP

NOTE: Qualified Version Definitions:

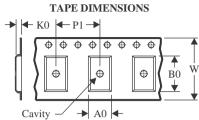
- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

### **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

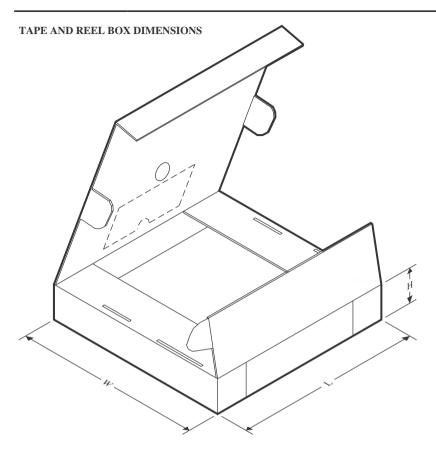


#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV04ATPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

### **PACKAGE MATERIALS INFORMATION**

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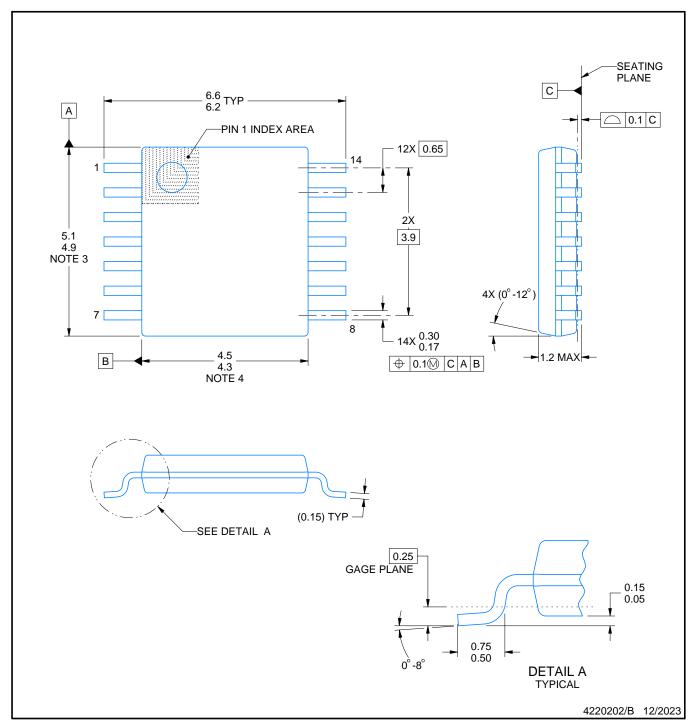


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LV04ATPWRG4Q1	TSSOP	PW	14	2000	353.0	353.0	32.0	



SMALL OUTLINE PACKAGE



#### NOTES:

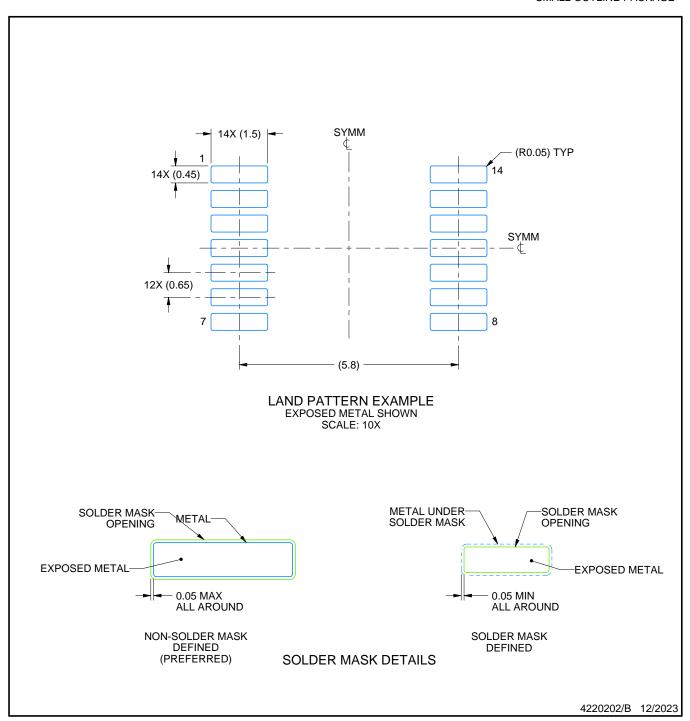
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



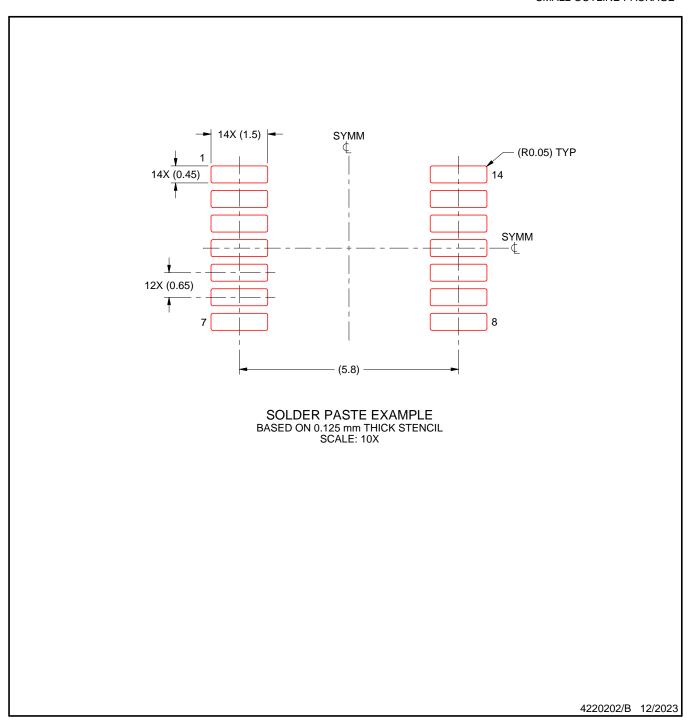
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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Last updated 10/2025